

ABSTRACT OF THE DISCLOSURE

A chip package mold chase, which includes a first mold chase and a second mold chase disposed oppositely to each other. The second mold chase includes a plurality of molding compound injecting units. The molding compound injecting units include at least
5 a first molding compound injecting unit and a second molding compound injecting unit, wherein the volume of the molding compound material accommodated by the first molding compound injecting unit is substantially equal to the volume of the molding compound material accommodated by the second molding compound injecting unit, and the quantity
10 of the chip package structures formed by the first molding compound injecting unit is greater than the quantity of the chip package structures formed by the second molding compound injecting unit.

Fig. 3